AMENDMENTS TO THE CLAIMS

Please amend the claims as set forth below. A complete listings of all claims are presented below.

1-21. (canceled)

22. (currently amended) A thin film semiconductor device comprising:

a product substrate and a thin film device,

wherein a manufacturing substrate is of an inorganic material,

wherein said product substrate is one of an organic material and a metal,

wherein said product substrate has a first side and a second side opposed to said first side,

wherein said manufacturing substrate is adjacent said first side, said manufacturing substrate being closer to said first side than to said second side,

wherein an adhesive layer is formed between said first side and said manufacturing substrate,

wherein said thin film device is adjacent said second side, said thin film device being closer to said second side than to said first side, ~~and~~

wherein said product substrate is between said thin film device and said manufacturing substrate, and

wherein said manufacturing substrate is removable for exposing said first side by leaving said product substrate and said thin film device.

23. (previously presented) A thin film semiconductor device as claimed in claim 22, wherein said manufacturing substrate is a glass substrate.

24. (previously presented) A thin film semiconductor device as claimed in claim 22, wherein said thin film device is a thin film transistor.

25. (previously presented) A thin film semiconductor device as claimed in claim 22, wherein said metal is aluminum.

26. (previously presented) A thin film semiconductor device as claimed in claim 22, wherein said organic material is a plastic.

27. (previously presented) A thin film semiconductor device as claimed in claim 26, wherein a moisture-proof buffer film is formed between said second surface and said thin film device.

28. (previously presented) A thin film semiconductor device as claimed in claim 26, wherein said plastic is from the group comprising polyether sulfone resin, polyethylene terephthalate resin and ARTON resin.

29-30. (canceled)

31. (previously amended) A thin film semiconductor device as claimed in claim 22, wherein said adhesive layer is from the group comprising a polyimide, Teflon resin, silicon, germanium and metal.

32. (previously presented) A liquid crystal display device comprising:

a product substrate and a pixel array,

wherein a manufacturing substrate is of an inorganic material,

wherein said product substrate is one of an organic material and a metal,

wherein said product substrate has a first side and a second side opposed to said first side,

wherein said manufacturing substrate is adjacent said first side, said manufacturing substrate being closer to said first side than to said second side,

wherein an adhesive layer is formed between said first side and said manufacturing substrate,

wherein said pixel array is adjacent said second side, said pixel array being closer to said second side than to said first side,

wherein said product substrate is between said pixel array and said manufacturing substrate, and

wherein said manufacturing substrate is removable for exposing said first side by leaving said product substrate and said pixel array.

33. (previously presented) A liquid crystal display device as claimed in claim 32, wherein said manufacturing substrate is a glass substrate.

34. (previously presented) A liquid crystal display device as claimed in claim 32, wherein said metal is aluminum.

35. (previously presented) A liquid crystal display device as claimed in claim 32, wherein said organic material is a plastic.

36. (previously presented) A liquid crystal display device as claimed in claim 35, wherein a moisture-proof buffer film is formed between said second surface and said pixel array.

37. (previously presented) A liquid crystal display device as claimed in claim 35, wherein said plastic is from the group comprising polyether sulfone resin, polyethylene terephthalate resin and ARTON resin.

38-39. (canceled)

40. (previously amended) A liquid crystal display device as claimed in claim 32, wherein said adhesive layer is from the group comprising a polyimide, Teflon resin, silicon, germanium and metal.

41. (previously presented) A electroluminescence display device comprising:

a product substrate and an electroluminescence device,

wherein a manufacturing substrate is of an inorganic material,

wherein said product substrate is one of an organic material and a metal,

wherein said product substrate has a first side and a second side opposed to said first side,

wherein said manufacturing substrate is adjacent said first side, said manufacturing substrate being closer to said first side than to said second side,

wherein said electroluminescence device is adjacent said second side, said electroluminescence device being closer to said second side than to said first side,

wherein an adhesive layer is formed between said first side and said manufacturing substrate,

wherein said product substrate is between said electroluminescence device and said manufacturing substrate, and

wherein said manufacturing substrate is removable for exposing said first side by leaving said product substrate and said electroluminescence device.

42. (previously presented) A electroluminescence display device as claimed in claim 41, wherein said manufacturing substrate is a glass substrate.

43. (previously presented) A electroluminescence display device as claimed in claim 41, wherein said metal is aluminum.

44. (previously presented) A electroluminescence display device as claimed in claim 41, wherein said organic material is a plastic.

45. (previously presented) A electroluminescence display device as claimed in claim 44, wherein a moisture-proof buffer film is formed between said second surface and said electroluminescence device.

46. (previously presented) A electroluminescence display device as claimed in claim 44, wherein said plastic is from the group comprising polyether sulfone resin, polyethylene terephthalate resin and ARTON resin.

47-48. (canceled)

49. (previously amended) A electroluminescence display device as claimed in claim 41, wherein said adhesive layer is from the group comprising a polyimide, Teflon resin, silicon, germanium and metal.

50. (previously presented) A thin film semiconductor device as claimed in claim 22, wherein said adhesive layer is dissolvable to remove said manufacturing substrate.

51. (previously presented) A liquid crystal display device as claimed in claim 32, wherein said adhesive layer is dissolvable to remove said manufacturing substrate.

52. (previously presented) A electroluminescence display device as claimed in claim 41, wherein said adhesive layer is dissolvable to remove said manufacturing substrate.